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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMKD4448 type contains three (3) Isolated High Speed Silicon Switching Diodes, manufactured by the epitaxial planar process, epoxy molded in an ULTRAmini[™] surface mount package, designed for applications requiring high speed switching applications.

MARKING CODE: K48

MAXIMUM RATINGS: (T _A =25°C) Continuous Reverse Voltage	SYMBOL V _R	75	UNITS V
Peak Repetitive Reverse Voltage	V _{RRM}	100	V
Continuous Forward Current	١ _F	250	mA
Peak Repetitive Forward Current	IFRM	500	mA
Peak Forward Surge Current, tp=1.0µs	IFSM	4.0	А
Peak Forward Surge Current, tp=1.0s	IFSM	1.0	А
Power Dissipation	PD	325	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +175	°C
Thermal Resistance	Θ_{JA}	461	°C/W

ELECTRICAL CHARACTERISTICS PER DIODE: (TA=25°C unless otherwise noted)

	MIN	MAX	UNITS nA
		25	IIA
I _R =5.0μΑ	75		V
I _R =100μΑ	100		V
I _F =100mA		1.0	V
V _R =0, f=1.0MHz		4.0	pF
$I_R=I_F=10$ mA, $I_{rr}=1.0$ mA, $R_L=100\Omega$		4.0	ns
	V_{R} =20V I_{R} =5.0µA I_{R} =100µA I_{F} =100mA V_{R} =0, f=1.0MHz	TEST CONDITIONS MIN V_R =20V 75 I_R =5.0µA 75 I_R =100µA 100 I_F =100mA VR=0, f=1.0MHz	$\begin{array}{c c} \mbox{TEST CONDITIONS} & \mbox{MIN} & \mbox{MAX} \\ V_R = 20V & 25 \\ I_R = 5.0 \mu A & 75 \\ I_R = 100 \mu A & 100 \\ I_F = 100 m A & 1.0 \\ V_R = 0, \ f = 1.0 \mbox{MHz} & 4.0 \end{array}$

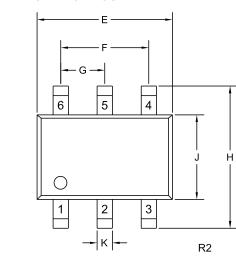
R6 (19-September 2011)





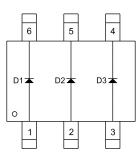
SURFACE MOUNT TRIPLE ISOLATED HIGH SPEED SILICON SWITCHING DIODES

С-



SOT-363 CASE - MECHANICAL OUTLINE





LEAD CODE:

Anode D1
Anode D2
Anode D3
Cathode D3
Cathode D2
Cathode D2
Cathode D1

MARKING CODE: K48

DIMENSIONS						
	INCHES		MILLIMETERS			
SYMBOL	MIN	MAX	MIN	MAX		
А	0.004	0.010	0.10	0.25		
В	0.005	-	0.12	-		
С	0.000	0.004	0.00	0.10		
D	0.031	0.043	0.80	1.10		
E	0.071	0.087	1.80	2.20		
F	0.051		1.30			
G	0.026		0.65			
Н	0.075	0.091	1.90	2.30		
J	0.043	0.055	1.10	1.40		
K	0.006	0.012	0.15	0.30		
SOT-363 (REV: R2)						

R6 (19-September 2011)

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OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

ss your design challenges.

· Custom product packing

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

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